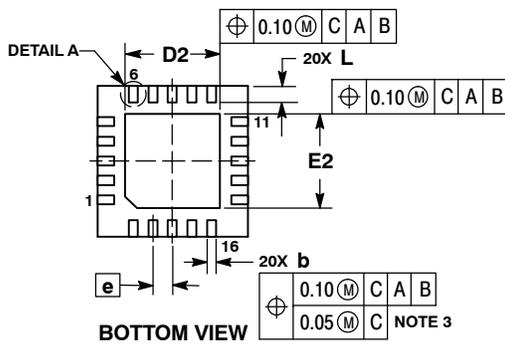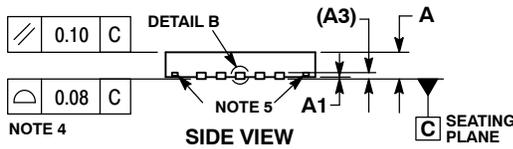**QFN20 5x5, 0.65P**
CASE 485DB
ISSUE O

DATE 02 APR 2013

SCALE 2:1

1   20

PIN ONE REFERENCE

| | 0.15 | C |

| | 0.15 | C |

TOP VIEW

| // | 0.10 | C |

DETAIL B

(A3)

| | 0.10 | C |

| | 0.08 | C |

NOTE 4

NOTE 5   A1

SIDE VIEW

A

C SEATING PLANE

DETAIL A
ALTERNATE TERMINAL
CONSTRUCTIONS

L1   L   L

DETAIL B
ALTERNATE
CONSTRUCTION
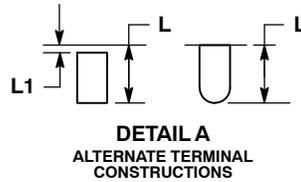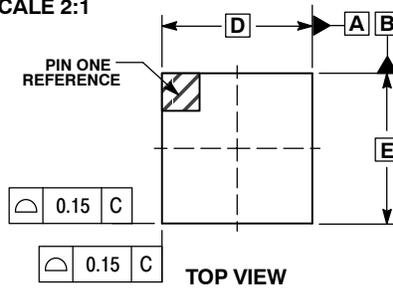
NOTES:
1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
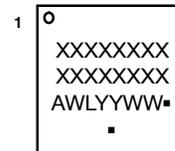5. OPTIONAL FEATURES.

| DIM | MILLIMETERS | |
	MIN	MAX
A	0.80	1.00
A1	---	0.05
A3	0.20 REF	
b	0.25	0.35
D	5.00 BSC	
D2	3.05	3.25
E	5.00 BSC	
E2	3.05	3.25
e	0.65 BSC	
L	0.45	0.65
L1	---	0.15

DETAIL A

| ⊕ | 0.10 Ⓜ | C | A | B |

D2

20X L

| ⊕ | 0.10 Ⓜ | C | A | B |

6

11

E2

1

16

e

20X b

| ⊕ | 0.10 Ⓜ | C | A | B |
| | 0.05 Ⓜ | C | NOTE 3 |

BOTTOM VIEW

GENERIC MARKING DIAGRAM*

1

O

XXXXXXXX
XXXXXXXX
AWLYYWW▪

▪

XXXXX = Specific Device Code
A   = Assembly Location
WL   = Wafer Lot
YY   = Year
WW   = Work Week
▪   = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*

5.30

3.30

20X
0.78

3.30

5.30

PACKAGE OUTLINE

0.65
PITCH

20X
0.40

DIMENSIONS: MILLIMETERS
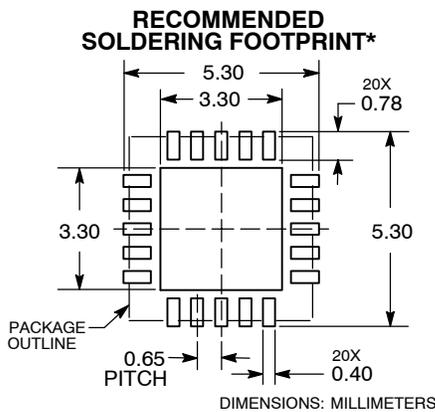
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	**98AON88183E**
STATUS:	**ON SEMICONDUCTOR STANDARD**
NEW STANDARD:	
DESCRIPTION:	**QFN20 5x5, 0.65P**

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. I. MARIANO.	02 APR 2013